



**SUD50N03-09P**  
Vishay Siliconix

**N-Channel 30-V (D-S) MOSFET**

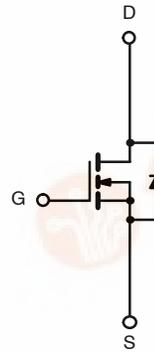
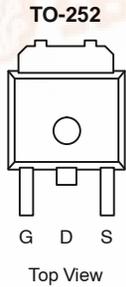
PRODUCT SUMMARY		
$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A) <sup>b</sup>
30	0.0095 @ $V_{GS} = 10$ V	63 <sup>b</sup>
	0.014 @ $V_{GS} = 4.5$ V	52 <sup>b</sup>

**FEATURES**

- TrenchFET® Power MOSFET
- Optimized for High- or Low-Side
- 100%  $R_g$  Tested

**APPLICATIONS**

- DC/DC Converters
- Synchronous Rectifiers



Ordering Information: SUD50N03-09P  
SUD50N03-09P—E3 (Lead Free)

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>a</sup>	$I_D$	$T_C = 25^\circ\text{C}$	63 <sup>b</sup>
		$T_C = 100^\circ\text{C}$	44.5 <sup>b</sup>
Pulsed Drain Current	$I_{DM}$	50	A
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	10	
Avalanche Current	$I_{AS}$	L = 0.1 mH	35
Single Pulse Avalanche Energy			$E_{AS}$
Maximum Power Dissipation	$P_D$	$T_C = 25^\circ\text{C}$	65.2
		$T_A = 25^\circ\text{C}$	7.5 <sup>a</sup>
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	$t \leq 10$ sec	16	$^\circ\text{C}/\text{W}$
		Steady State	40	
Maximum Junction-to-Case	$R_{thJC}$	1.8	2.3	

Notes:  
<sup>a</sup> Surface Mounted on FR4 Board,  $t \leq 10$  sec.  
<sup>b</sup> Based on maximum allowable Junction Temperature, package limitation current is 50 A.

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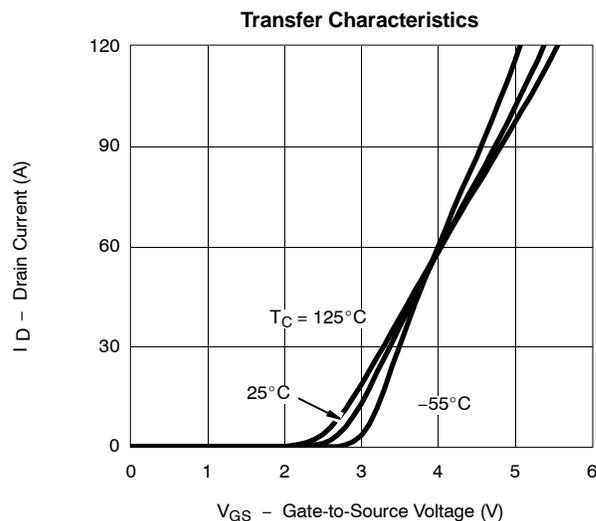
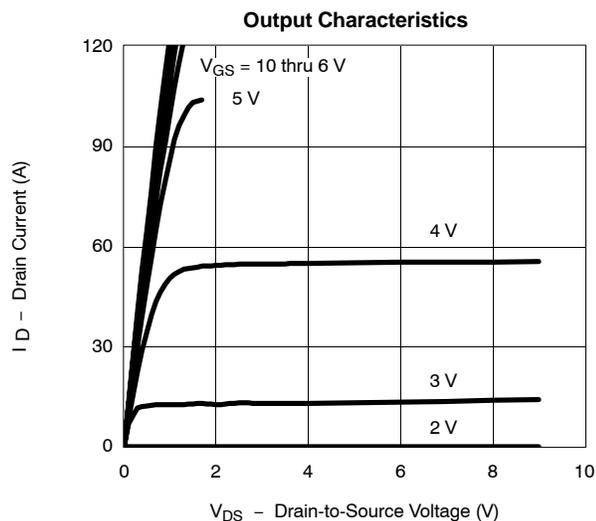
## SPECIFICATIONS (T<sub>J</sub> = 25 °C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ <sup>a</sup>	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.0		3.0	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	50			A
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0076	0.0095	Ω
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C			0.015	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A		0.0115	0.014	
Forward Transconductance <sup>b</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A	20			S
<b>Dynamic<sup>a</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		2200		pF
Output Capacitance	C <sub>oss</sub>			410		
Reverse Transfer Capacitance	C <sub>rss</sub>			180		
Total Gate Charge <sup>c</sup>	Q <sub>g</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 50 A		11	16	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			7.5		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			5.0		
Gate Resistance	R <sub>g</sub>		0.5	1.5	2.1	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, R <sub>L</sub> = 0.3 Ω I <sub>D</sub> ≅ 50 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 2.5 Ω		9	15	ns
Rise Time <sup>c</sup>	t <sub>r</sub>			80	120	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			22	35	
Fall Time <sup>c</sup>	t <sub>f</sub>			8	12	
<b>Source-Drain Diode Ratings and Characteristic (T<sub>C</sub> = 25 °C)</b>						
Pulsed Current	I <sub>SM</sub>				100	A
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 50 A, V <sub>GS</sub> = 0 V		1.2	1.5	V
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, di/dt = 100 A/μs		35	70	ns

**Notes**

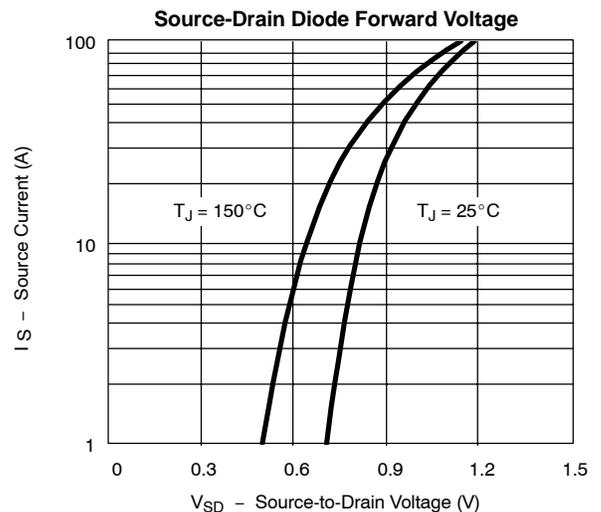
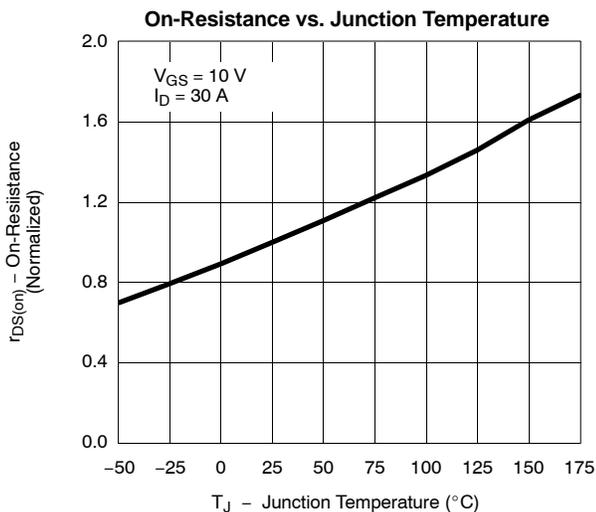
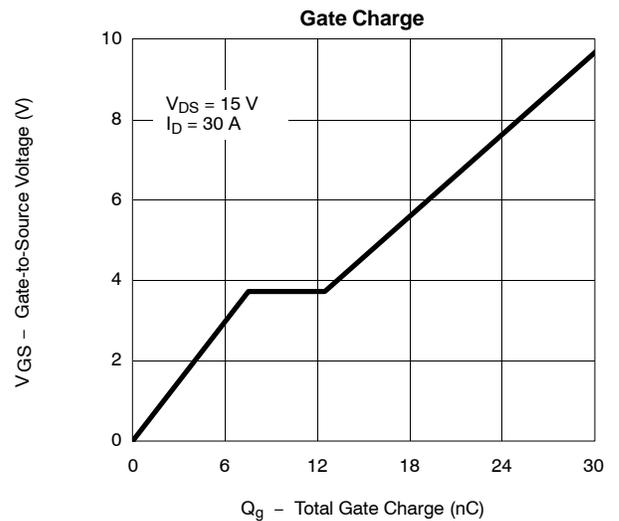
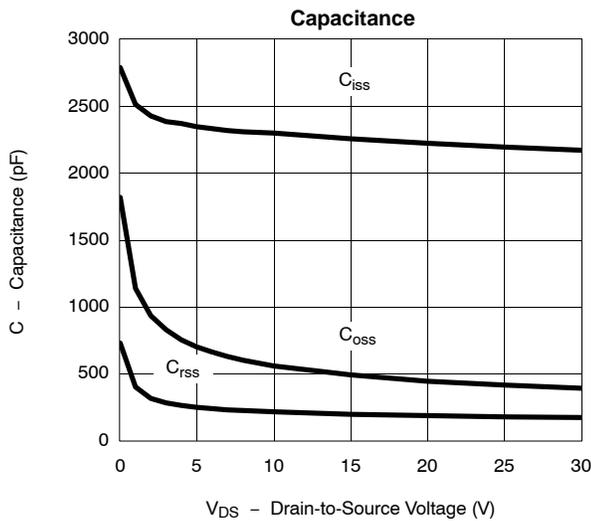
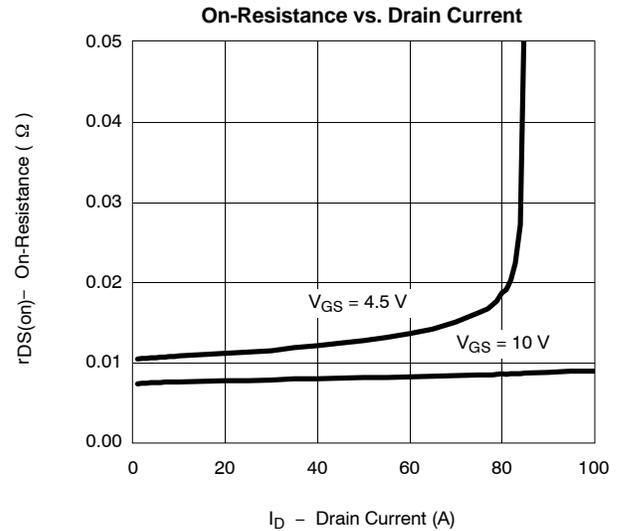
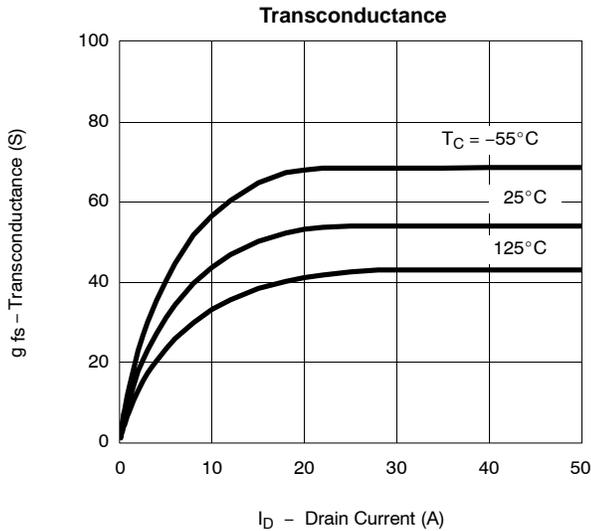
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- c. Independent of operating temperature.

## TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)





**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**





**THERMAL RATINGS**

